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(71) Applicant (for all designated States except US): **KONINKLIJKE PHILIPS ELECTRONICS, N.V. [NL/NL]; Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).**

(71) Applicant (for AE only): **U.S. PHILIPS CORPORATION [US/US]; 1251 Avenue of the Americas, New York, New York 10020 (US).**

(72) Inventor; and

(75) Inventor/Applicant (for US only): **THOONEN, Henk [NL/NL]; Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).**

(74) Common Representative: **KONINKLIJKE PHILIPS ELECTRONICS, N.V.; c/o LESTER, Shannon, 1109 McKay Drive, M/S-SJ41, San Jose, California 95131-1706 (US).**

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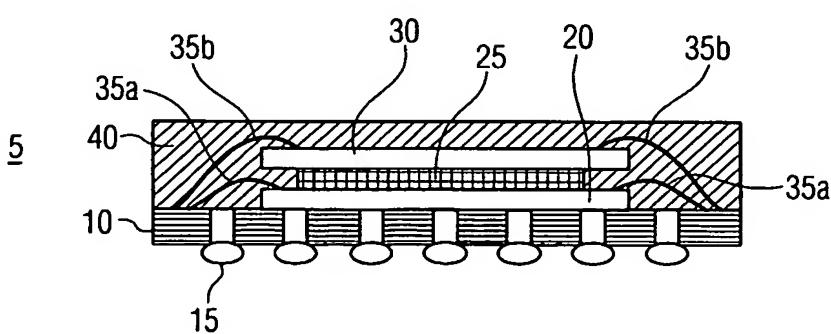
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— as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations

[Continued on next page]

(54) Title: ELECTRICAL SHIELDING IN STACKED DIES BY USING CONDUCTIVE DIE ATTACH ADHESIVE



WO 2005/034238 A1

The additional device die is die attached to the first device die. The ground connections of the first device die are connected to the ground connections of the additional device die in order to minimize the electrical interference between the device dies. An additional feature of the embodiment is, ground connections of the first device are connected to the ground connections of the additional device with a conductive adhesive (25).

(57) Abstract: In example embodiment, there is an integrated circuit (IC) device (5) assembled in a package (5) having a plurality of die including a first device (20) and at least one additional device (30). The IC comprises a substrate (10). A first device die (20), having bonding pads including ground connections, is die attached to the substrate (10). An additional device die (30), having bonding pads including ground connections is disposed on top of the first device die (20).



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